



DT2636-04S

4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY

Features

- IEC 61000-4-2 (ESD): Air ±20kV, Contact ±18kV
- 4 Channels of ESD Protection
- Low Channel Input Capacitance of 0.65pF Typical
- Typically Used at High Speed Ports such as USB 2.0, IEEE1394, Serial ATA, DVI, HDMI, PCI
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

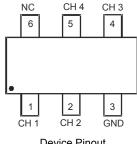
Mechanical Data

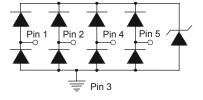
- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.006 grams (approximate)





Top View





Device Pinout

Device Schematic

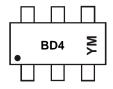
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|--------------|--------|------------------|
| DT2636-04S-7 | SOT363 | 3000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



BD4 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013)M = Month (ex: 9 = September)

Date Code Key

| Year | 2013 | 3 | 2014 | | 2015 | 20 | 16 | 2017 | | 2018 | 2 | 2019 |
|-------|------|-----|------|-----|------|-----|-----|------|-----|------|-----|------|
| Code | Α | | В | | С | [|) | E | | F | | G |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Maximum Ratings (@T_A = +25°C, unless otherwise specified)

| Characteristic | Symbol | Value | Unit | Conditions |
|------------------------------------|--------------------------|-------------|------|------------------------|
| Peak Pulse Current | I _{PP} | 6.5 | Α | 8/20µs, From CH to GND |
| Peak Pulse Current | I _{PP} | 6.5 | Α | 8/20µs, From GND to CH |
| Peak Pulse Power | P _{PP} | 60 | W | 8/20µs, From CH to GND |
| ESD Protection – Contact Discharge | V _{ESD_Contact} | ±18 | kV | Standard IEC 61000-4-2 |
| ESD Protection – Air Discharge | V _{ESD_Air} | ±20 | kV | Standard IEC 61000-4-2 |
| Operating Temperature | T _{OP} | -55 to +85 | °C | _ |
| Storage Temperature | T _{STG} | -55 to +150 | °C | _ |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|--|---------------|-------|------|
| Power Dissipation Typical (Note 5) | P_{D} | 200 | mW |
| Thermal Resistance, Junction to Ambient Typical (Note 5) | $R_{	hetaJA}$ | 625 | °C/W |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified)

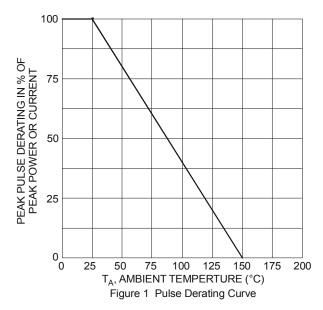
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Conditions |
|---------------------------------------|-----------------------|-----|------|-----|------|--|
| Reverse Standoff Voltage | V_{RWM} | _ | _ | 5.5 | V | _ |
| Channel Leakage Current (Note 6, 7) | I _R | _ | 1 | 10 | nA | V _R = 2.5V |
| Reverse Breakdown Voltage | V _{BR} | 7.0 | _ | 9.5 | V | I _R = 1mA, from CH to GND |
| Clamping Voltage, Positive Transients | V _{CL1} | _ | 6.8 | _ | V | I_{PP} = 1A, t_p = 8/20 μ s |
| Clamping Voltage, Positive Transients | V _{CL1} | _ | 9 | _ | V | $I_{PP} = 5A, t_p = 8/20 \mu s$ |
| Clamping Voltage, Negative Transients | V _{CL2} | _ | 1.5 | _ | V | I_{PP} = 1A, t_p = 8/20 μ s |
| Forward Voltage | VF | _ | 0.7 | _ | V | I _F = 1mA, GND to CH |
| Dynamic Resistance | R _{DIFF} | _ | 0.4 | _ | Ω | I_{PP} = 1A, t_p = 8/20 μ s, CH to GND |
| Dynamic Resistance | R _{DIFF-R} | _ | 0.45 | _ | Ω | TLP, 20A, tp = 100 ns, CH to GND |
| Dynamic Resistance | R _{DIFF-F} | _ | 0.2 | _ | Ω | TLP, 20A, tp = 100 ns, GND to CH |
| CII to CND Consoitones | 6 | _ | 0.75 | _ | pF | V _(CH-GND) = 0V, f = 1MHz |
| CH to GND Capacitance | C _(CH-GND) | _ | 0.65 | 0.9 | pF | V _(CH-GND) = 2.5V, f = 1MHz |
| Delta Ссн | Сснмах- Сснмім | _ | 0.04 | _ | pF | C _{CHMAX} -C _{CHMIN} |

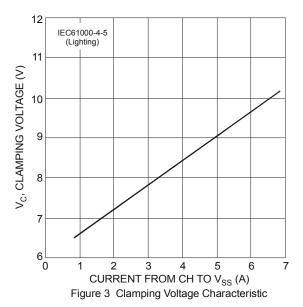
Notes:

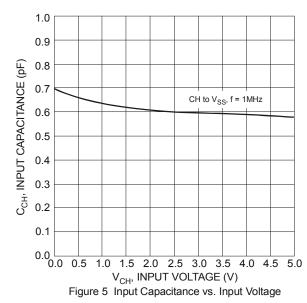
^{5.} Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

^{6.} Short duration pulse test used to minimize self-heating effect.
7. Measured from pin 1, 2, 4 and 5 to GND.









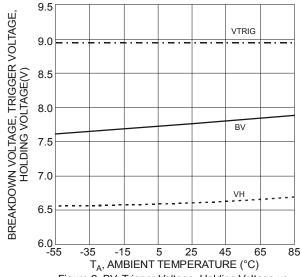


Figure 2 BV, Trigger Voltage, Holding Voltage vs. Ambient Temperature

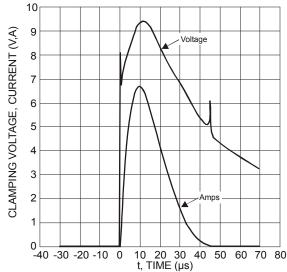
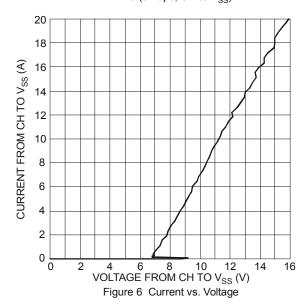


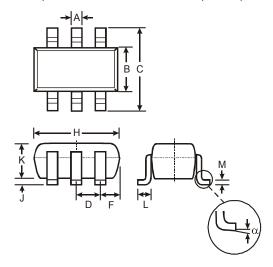
Figure 4 Waveform of Clamping Voltage, Current vs. Time (8/20 μ s, CH to V $_{\rm SS}$)





Package Outline Dimensions

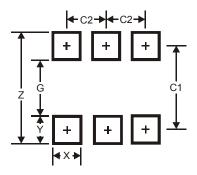
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



| SOT363 | | | | | | |
|----------------------|----------|------|-------|--|--|--|
| Dim | Min | Max | Тур | | | |
| Α | 0.10 | 0.30 | 0.25 | | | |
| В | 1.15 | 1.35 | 1.30 | | | |
| U | 2.00 | 2.20 | 2.10 | | | |
| D | 0.65 Typ | | | | | |
| F | 0.40 | 0.45 | 0.425 | | | |
| Н | 1.80 | 2.20 | 2.15 | | | |
| 7 | 0 | 0.10 | 0.05 | | | |
| K | 0.90 | 1.00 | 1.00 | | | |
| Ь | 0.25 | 0.40 | 0.30 | | | |
| М | 0.10 | 0.22 | 0.11 | | | |
| α | 0° | 8° | - | | | |
| All Dimensions in mm | | | | | | |

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| Z | 2.5 |
| G | 1.3 |
| Х | 0.42 |
| Υ | 0.6 |
| C1 | 1.9 |
| C2 | 0.65 |



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